

## Claims

We claim:

5 1. A semiconductor package comprising:

*Substrate*  
a package substrate having a first surface;

0 an integrated circuit electrically coupled to the first surface of the package substrate, the  
integrated circuit and the package substrate together forming the semiconductor  
package; and

15 a first inductance circuit formed within the semiconductor package; and

20 a second inductance circuit formed within the semiconductor package,

wherein the first inductance circuit is coupled in parallel to the second inductance circuit,  
and

20 wherein the first and second inductance circuits have substantially symmetrical geometric  
characteristics.

2. A semiconductor package comprising:

a package substrate having a first surface;

5 an integrated circuit electrically connected to said first surface of said package substrate, said integrated circuit and said package substrate together forming said semiconductor package, the integrated circuit and package substrate including frequency synthesizer circuitry; and

at least one inductance circuit formed entirely within said semiconductor package and formed at least partially between said integrated circuit and said package substrate, the inductance circuit at least in part determining an output frequency for the frequency synthesizer circuitry;

wherein said frequency synthesizer circuitry has an output frequency selectively operable within a plurality of bands, and wherein said at least one inductance circuit forms part of a controlled oscillator circuit within said frequency synthesizer circuitry, the output frequency being dependent upon the controlled oscillator circuit.

*Add a<sup>5</sup> 7*